

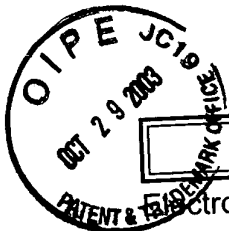
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Electronic Patent Application Submission
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EFS ID: 49915
Application ID: 09912844
Title of Invention: HIGH PRESSURE PROCESSING
CHAMBER FOR SEMICONDUCTOR
SUBSTRATE
First Named Inventor: Maximilian Biberger
Domestic/Foreign Application: Domestic Application
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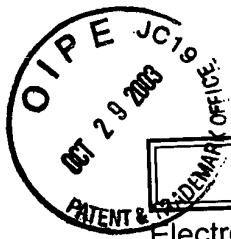
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Title of Invention	HIGH PRESSURE PROCESSING CHAMBER FOR SEMICONDUCTOR SUBSTRATE									
Application Number: 09/912844 										
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<table border="1"><thead><tr><th>Submitted by:</th><th>Elec. Sign.</th><th>Sign. Capacity</th></tr></thead><tbody><tr><td>Thomas B. Haverstock Registered Number: 32571</td><td>/tbh/</td><td>Attorney</td></tr></tbody></table>			Submitted by:	Elec. Sign.	Sign. Capacity	Thomas B. Haverstock Registered Number: 32571	/tbh/	Attorney		
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Comments										



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Electronic Version v18

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<h3>US Patent Documents</h3> <p>Note: Applicant is not required to submit a paper copy of cited US Patent Documents</p> <table border="1"><thead><tr><th>init</th><th>Cite.No.</th><th>Patent No.</th><th>Date</th><th>Patentee</th><th>Kind</th><th>Class</th><th>Subclass</th></tr></thead><tbody><tr><td></td><td>1</td><td>5193560</td><td>1993-03-16</td><td>Tanaka et al.</td><td></td><td></td><td></td></tr><tr><td></td><td>2</td><td>5195878</td><td>1993-03-23</td><td>Sahiavo et al.</td><td></td><td></td><td></td></tr><tr><td></td><td>3</td><td>5213485</td><td>1993-05-25</td><td>Wilden</td><td></td><td></td><td></td></tr><tr><td></td><td>4</td><td>5221019</td><td>1993-06-22</td><td>Pechacek</td><td></td><td></td><td></td></tr><tr><td></td><td>5</td><td>5222876</td><td>1993-06-29</td><td>Budde</td><td></td><td></td><td></td></tr><tr><td></td><td>6</td><td>5224504</td><td>1993-07-06</td><td>Thompson et al.</td><td></td><td></td><td></td></tr><tr><td></td><td>7</td><td>5236669</td><td>1993-08-17</td><td>Simmons et al.</td><td></td><td></td><td></td></tr><tr><td></td><td>8</td><td>5240390</td><td>1993-08-31</td><td>Kvinge et al.</td><td></td><td></td><td></td></tr><tr><td></td><td>9</td><td>5243821</td><td>1993-09-14</td><td>Schuck et al.</td><td></td><td></td><td></td></tr><tr><td></td><td>10</td><td>5246500</td><td>1993-09-21</td><td>Samata et al.</td><td></td><td></td><td></td></tr><tr><td></td><td>11</td><td>5251776</td><td>1993-10-12</td><td>Morgan Jr. et al.</td><td></td><td></td><td></td></tr><tr><td></td><td>12</td><td>5280693</td><td>1994-01-25</td><td>Heudecker</td><td></td><td></td><td></td></tr><tr><td></td><td>13</td><td>5285352</td><td>1994-02-08</td><td>Pastore et al.</td><td></td><td></td><td></td></tr></tbody></table>					init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass		1	5193560	1993-03-16	Tanaka et al.					2	5195878	1993-03-23	Sahiavo et al.					3	5213485	1993-05-25	Wilden					4	5221019	1993-06-22	Pechacek					5	5222876	1993-06-29	Budde					6	5224504	1993-07-06	Thompson et al.					7	5236669	1993-08-17	Simmons et al.					8	5240390	1993-08-31	Kvinge et al.					9	5243821	1993-09-14	Schuck et al.					10	5246500	1993-09-21	Samata et al.					11	5251776	1993-10-12	Morgan Jr. et al.					12	5280693	1994-01-25	Heudecker					13	5285352	1994-02-08	Pastore et al.			
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	14	5288333	1994-02-22	Tanaka et al.
	15	5339844	1994-08-23	Stanford Jr. et al.
	16	5370741	1994-12-06	Bergman
	17	5412958	1995-05-09	Iliff et al.
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	19	5447294	1995-09-05	Sakata et al.
	20	5503176	1996-04-02	Dunmire et al.
	21	5505219	1996-04-09	Lansberry et al.
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	23	5571330	1996-11-05	Kyogoku
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	32	5706319	1998-01-06	Holtz
	33	5746008	1998-05-05	Yamashita et al.

Remarks

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